

Planar Package Structure for High Power Light Emitting Diode

ABSTRACT

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A planar package structure for high power light emitting diode, comprising:
a substrate; a package material; a light emitting diode chip disposed on the
substrate, having a main light emitting surface served as a light source; and a
planar optical modulation unit disposed on the package material, so that the
planar optical modulation unit is above the main light emitting surface, and
utilized for modulating the optical phase of the light source. The planar
optical modulation unit can perform a refractive optical phase modulation or
a diffractive optical phase modulation such that a thin and planar high power
light emitting diode package element with function of optical phase
modulation is obtained.